Titles of Most Frequently Occurring Classifications of Patents Returne

From A Search of 09681304 on March 13, 2002

12 438/52 (3 OR, 9 XR)Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS 438/48 MAKING DEVICE OR CIRCUIT RESPONSIVE TO NONELECTRICAL SIGNAL 438/50 .Physical stress responsive 438/52 .. Having cantilever element 11 310/307 (10 OR, 1 XR) 310 : ELECTRICAL GENERATOR OR MOTOR STRUCTURE Class 310/300 NON-DYNAMOELECTRIC 310/306 .Thermal or pyromagnetic 310/307 .. With heat actuated bimetal element 10 438/50 (4 OR, 6 XR) 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS Class 438/48 MAKING DEVICE OR CIRCUIT RESPONSIVE TO NONELECTRICAL SIGNAL 438/50 .Physical stress responsive 216/2 (4 OR, 5 XR) Class 216 : ETCHING A SUBSTRATE: PROCESSES ETCHING OF SEMICONDUCTOR MATERIAL TO PRODUCE A 216/2 Ν ARTICLE HAVING A NONELECTRICAL FUNCTION 257/417 (2 OR, 7 XR) Class 257 : ACTIVE SOLID-STATE DEVICES RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G., 257/414 CHEMICAL, STRESS, LIGHT, OR MAGNETIC FIEL D SENSORS) 257/415 .Physical deformation 257/417 ..Strain sensors 310/40MM (3 OR, 4 XR) 310 : ELECTRICAL GENERATOR OR MOTOR STRUCTURE Class 310/10 DYNAMOELECTRIC 310/40R .Rotary ..Miniature motors 310/40MM 257/415 (3 OR, 3 XR)

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257 : ACTIVE SOLID-STATE DEVICES

Class

257/414 RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G., CHEMICAL, STRESS, LIGHT, OR MAGNETIC FIELD

SENSORS)

257/415 .Physical deformation

6 438/455 (1 OR, 5 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/455 BONDING OF PLURAL SEMICONDUCTOR SUBSTRATES

5 156/345 (2 OR, 3 XR)

Class 156: ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL MANUFACTURE

156/345 DIFFERENTIAL ETCHING APPARATUS

4 73/514.36 (0 OR, 4 XR)

Class 073: MEASURING AND TESTING

73/488 SPEED, VELOCITY, OR ACCELERATION

73/514.01 .Acceleration determination utilizing inertial element

73/514.36 ..Pendulum or beam

4 118/723IR (2 OR, 2 XR)

Class 118: COATING APPARATUS

118/715 GAS OR VAPOR DEPOSITION

118/722 .With treating means (e.g., jarring)

118/723R ..By creating electric field (e.g., gas

activation, plasma, etc.)

118/723I ...Radio frequency antenna or radio frequency

inductive coil discharge means

118/723IRProducing energized gas remotely located

from substrate

4 118/728 (0 OR, 4 XR)

Class 118 : COATING APPARATUS

118/715 GAS OR VAPOR DEPOSITION

118/728 .Work support

4 257/254 (1 OR, 3 XR)

Class 257: ACTIVE SOLID-STATE DEVICES

257/213 FIELD EFFECT DEVICE

257/252 .Responsive to non-optical, non-electrical

signal

257/254 .. Physical deformation (e.g., strain sensor,

acoustic wave detector)

4 310/306 (1 OR, 3 XR)

Class 310 : ELECTRICAL GENERATOR OR MOTOR STRUCTURE

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09681304 CLSTITLES
                      NON-DYNAMOELECTRIC
        310/300
        310/306
                       .Thermal or pyromagnetic
  438/460
                (3 \text{ OR}, 1 \text{ XR})
                438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
        Class
        438/460
                      SEMICONDUCTOR SUBSTRATE DICING
  438/526
                 (1 \text{ OR}, 3 \text{ XR})
                438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
        Class
        438/510
                       INTRODUCTION OF CONDUCTIVITY MODIFYING DOPANT
                            INTO SEMICONDUCTIVE MATERIAL
                       .Ion implantation of dopant into semiconductor
        438/514
                           region
        438/526
                       .. Forming buried region
 438/53
                 (1 OR, 3 XR)
                438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
        Class
        438/48
                      MAKING DEVICE OR CIRCUIT RESPONSIVE TO
                            NONELECTRICAL SIGNAL
                       .Physical stress responsive
        438/50
                       .. Having diaphragm element
        438/53
                (2 OR, 1 XR)
3
    73/514.21
                073 : MEASURING AND TESTING
        Class
                       SPEED, VELOCITY, OR ACCELERATION
        73/488
                       .Acceleration determination utilizing inertial
        73/514.01
                             element
                       .. Specific type of electric sensor or specific
        73/514.16
                            type of magnetic sensor
                       ...Rebalance
        73/514.17
        73/514.21
                       ....Pendulum or beam
                (2 OR, 1 XR)
  118/723E
                118 : COATING APPARATUS
        Class
        118/715
                       GAS OR VAPOR DEPOSITION
                       .With treating means (e.g., jarring)
        118/722
                       .. By creating electric field (e.g., gas
        118/723R
                           activation, plasma, etc.)
                       ... Having glow discharge electrodes (e.g., DC,
        118/723E
                          AC, RF, etc.)
3 118/723I
                 (0 \text{ OR}, 3 \text{ XR})
        Class 118: COATING APPARATUS
        118/715
                      GAS OR VAPOR DEPOSITION
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118/722

.With treating means (e.g., jarring)

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09681304 CLSTITLES
          118/723R
                        .. By creating electric field (e.g., gas
                            activation, plasma, etc.)
          118/723I
                        ... Radio frequency antenna or radio frequency
                           inductive coil discharge means
                   (0 OR, 3 XR)
    118/723MP
                  118 : COATING APPARATUS
          Class
          118/715
                        GAS OR VAPOR DEPOSITION
          118/722
                        .With treating means (e.g., jarring)
          118/723R
                        .. By creating electric field (e.g., gas
                            activation, plasma, etc.)
          118/723MP
                         ...Multiple gas energizing means associated
                           with one deposition site (i.e., excluding s
ubstrate heater
                           as an energizing means)
    118/733
                   (0 \text{ OR}, 3 \text{ XR})
          Class
                  118 : COATING APPARATUS
          118/715
                        GAS OR VAPOR DEPOSITION
          118/733
                        .Chamber seal
                   (3 OR, 0 XR)
    148/33.2
                  148 : METAL TREATMENT
          Class
          148/33
                        BARRIER LAYER STOCK MATERIAL, P-N TYPE
          148/33.2
                        .With recess, void, dislocation, grain
                           boundaries or channel openings
    156/247
                   (0 \text{ OR}, 3 \text{ XR})
          Class
                  156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL
                          MANUFACTURE
          156/1
                        METHODS
          156/60
                        .Surface bonding and/or assembly therefor
                         ..With stripping of adhered lamina
          156/247
  3 156/267
                   (0 OR, 3 XR)
                  156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL
          Class
                          MANUFACTURE
          156/1
                        METHODS
                        .Surface bonding and/or assembly therefor
          156/60
                         .. With cutting, punching, tearing or severing
          156/250
                        ...Flash, trim or excess removal
          156/267
                   (2 OR, 1 XR)
    200/181
                  200 : ELECTRICITY: CIRCUIT MAKERS AND BREAKERS
                        ELECTROSTRICTIVE OR ELECTROSTATIC
          200/181
  3 204/298.15 (1 OR, 2 XR)
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			Class 204/193 204/298. 204/298. 204/298.	01	Coating
	3	216/6		216	OR, 3 XR) : ETCHING A SUBSTRATE: PROCESSES GAS PHASE ETCHING OF SUBSTRATE .Application of energy to the gaseous etchant or to the substrate being etchedUsing plasma
	3	271/3		271	OR, 1 XR) : SHEET FEEDING OR DELIVERING DELIVERING .By pneumatic conveyor
	3	271/:		271	OR, 3 XR) : SHEET FEEDING OR DELIVERING DELIVERING .By pneumatic conveyorUsing pressurized gas
	3	310/3	Class 310/300	310	OR, 1 XR) : ELECTRICAL GENERATOR OR MOTOR STRUCTURE NON-DYNAMOELECTRIC .Charge accumulatingElectrostatic
	3	310/	Class	310	OR, 3 XR) : ELECTRICAL GENERATOR OR MOTOR STRUCTURE Printed-circuit motors and components
	3	359/2			OR, 2 XR) : OPTICS: SYSTEMS DEFLECTION USING A MOVING ELEMENT OR MEDIUM (OFFSETTING OR CHANGING AT LEAST A PORTIO
N	OF	THE I	359/223 359/224		By moving a reflective element Reflective element moved by deformable support
	3	359/2		359	OR, 3 XR) : OPTICS: SYSTEMS LIGHT CONTROL BY OPAQUE ELEMENT OR MEDIUM MOVABLE IN OR THROUGH LIGHT PATH
			359/230		.Electro-mechanical

3 ent	359/290 Class 359/237 359/238 359/290	359	OR, 3 XR) : OPTICS: SYSTEMS OPTICAL MODULATOR .Light wave temporal modulation (e.g., frequency, amplitude, etc.) .By changing physical characteristics (e.g., shape, size or contours) of an optical elem
3	359/291 Class 359/237 359/238	359	OR, 1 XR) : OPTICS: SYSTEMS OPTICAL MODULATOR .Light wave temporal modulation (e.g., frequency, amplitude, etc.)By changing physical characteristics (e.g.,
ment	359/291		<pre>shape, size or contours) of an optical eleShape or contour of light control surface altered</pre>
3	Class		OR, 1 XR) : RADIATION IMAGERY CHEMISTRY: PROCESS, COMPOSITION, OR PRODUCT THEREOF
R	430/22		REGISTRATION OR LAYOUT PROCESS OTHER THAN COLO PROOFING
3	438/458 Class		OR, 1 XR) : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
	438/455 438/458		BONDING OF PLURAL SEMICONDUCTOR SUBSTRATES .Subsequent separation into plural bodies (e.g., delaminating, dicing, etc.)
3			OR, 3 XR) : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
	438/455 438/459		BONDING OF PLURAL SEMICONDUCTOR SUBSTRATES .Thinning of semiconductor substrate
3	438/48 Class		OR, 3 XR) : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
	438/48		MAKING DEVICE OR CIRCUIT RESPONSIVE TO NONELECTRICAL SIGNAL
3	438/515	(3	OR, 0 XR)

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09681304 CLSTITLES
          Class
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          438/510
                         INTRODUCTION OF CONDUCTIVITY MODIFYING DOPANT
                              INTO SEMICONDUCTIVE MATERIAL
          438/514
                         .Ion implantation of dopant into semiconductor
                             region
                         .. Ionized molecules
          438/515
    438/706
                  (0 \text{ OR}, 3 \text{ XR})
          Class
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          438/689
                        CHEMICAL ETCHING
          438/706
                        .Vapor phase etching (i.e., dry etching)
    438/712
                  (0 \text{ OR}, 3 \text{ XR})
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          Class
          438/689
                        CHEMICAL ETCHING
          438/706
                         .Vapor phase etching (i.e., dry etching)
          438/707
                         .. Utilizing electromagnetic or wave energy
                         ... By creating electric field (e.g., plasma,
          438/710
                             glow discharge, etc.)
          438/712
                         .... Reactive ion beam etching (i.e., RIBE)
  3 438/739
                  (0 \text{ OR}, 3 \text{ XR})
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          Class
          438/689
                        CHEMICAL ETCHING
          438/706
                         .Vapor phase etching (i.e., dry etching)
          438/735
                         ..Differential etching of semiconductor
                               substrate
          438/737
                         ... Substrate possessing multiple layers
          438/738
                         .... Selectively etching substrate possessing
                             multiple layers of differing etch characte
ristics
          438/739
                         .....Lateral etching of intermediate layer
                            (i.e., undercutting)
    445/24
  3
                   (1 OR, 2 XR)
                  445 : ELECTRIC LAMP OR SPACE DISCHARGE COMPONENT OR
          Class
                           DEVICE MANUFACTURING
          445/1
                        PROCESS
          445/23
                         .With assembly or disassembly
          445/24
                         .. Display or gas panel making
      29/596
                  (0 OR, 2 XR)
                  029 : METAL WORKING
          Class
          29/592
                        METHOD OF MECHANICAL MANUFACTURE
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09681304 CLSTITLES
                      .Electrical device making
        29/592.1
                      .. Dynamoelectric machine
        29/596
2
    29/598
                 (1 \text{ OR}, 1 \text{ XR})
                029 : METAL WORKING
        Class
        29/592
                      METHOD OF MECHANICAL MANUFACTURE
        29/592.1
                      .Electrical device making
        29/596
                      .. Dynamoelectric machine
        29/598
                      ...Rotor
2
    73/514.16
                (2 OR, 0 XR)
        Class
                073 : MEASURING AND TESTING
                      SPEED, VELOCITY, OR ACCELERATION
        73/488
                      .Acceleration determination utilizing inertial
        73/514.01
                          element
        73/514.16
                      .. Specific type of electric sensor or specific
                         type of magnetic sensor
    73/514.32
                (0 OR, 2 XR)
2
        Class
                073 : MEASURING AND TESTING
                      SPEED, VELOCITY, OR ACCELERATION
        73/488
                      .Acceleration determination utilizing inertial
        73/514.01
                      .. Specific type of electric sensor or specific
        73/514.16
                          type of magnetic sensor
        73/514.32
                      ... Capacitive sensor
    73/654
                (0 OR, 2 XR)
                073 : MEASURING AND TESTING
        Class
        73/570
                      VIBRATION
        73/649
                      .Sensing apparatus
                      ..With inertia element
        73/652
        73/654
                      ...With electrically controlled indicator
 156/230
                (0 OR, 2 XR)
                156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL
        Class
                        MANUFACTURE
        156/1
                      METHODS
                      .Surface bonding and/or assembly therefor
        156/60
                      ..Direct contact transfer of adhered lamina
        156/230
                         from carrier to base
2 156/233
                 (0 OR, 2 XR)
                156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL
        Class
                        MANUFACTURE
        156/1
                      METHODS
                      .Surface bonding and/or assembly therefor
        156/60
                      ..Direct contact transfer of adhered lamina
        156/230
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from carrier to base

156/233 ... Metal foil lamina

156/241 (2 OR, 0 XR)

> Class 156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL

MANUFACTURE

156/1 METHODS

156/60 .Surface bonding and/or assembly therefor

156/230 ..Direct contact transfer of adhered lamina

from carrier to base

156/241 ... To base coated with adhesive

2 156/250 (0 OR, 2 XR)

> Class 156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL

> > MANUFACTURE

156/1 METHODS

156/60 .Surface bonding and/or assembly therefor

156/250 .. With cutting, punching, tearing or severing

2 156/256 (0 OR, 2 XR)

> 156: ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL Class

> > MANUFACTURE

METHODS 156/1

156/60 .Surface bonding and/or assembly therefor

.. With cutting, punching, tearing or severing 156/250

156/256 ... Prior to assembly

2 156/344 (1 OR, 1 XR)

> 156: ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL Class

> > MANUFACTURE

156/1 **METHODS**

156/344 .Delaminating, per se

204/192.32 (0 OR, 2 XR)

204: CHEMISTRY: ELECTRICAL AND WAVE ENERGY

.Coating, forming or etching by sputtering 204/192.1

204/192.32 .. Sputter etching

204/192.37 (2 OR, 0 XR)

> 204 : CHEMISTRY: ELECTRICAL AND WAVE ENERGY Class

204/192.1 .Coating, forming or etching by sputtering

204/192.32 .. Sputter etching

204/192.32 ...Sputter etching 204/192.35 ...Etching specified ma 204/192.37Silicon containing ... Etching specified material

2 204/298.32 (0 OR, 2 XR)

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09681304 CLSTITLES
                 204 : CHEMISTRY: ELECTRICAL AND WAVE ENERGY
         Class
         204/193
                       APPARATUS
                     .Coating, forming or etching by sputtering
         204/298.01
         204/298.31
                       .. Etching
         204/298.32
                       ... Measuring, analyzing or testing
   204/298.36
                 (0 OR, 2 XR)
                 204 : CHEMISTRY: ELECTRICAL AND WAVE ENERGY
         Class
         204/193
                       APPARATUS
         204/298.01
                       .Coating, forming or etching by sputtering
         204/298.31
                      ..Etching
         204/298.36
                       ... Beam or directed flux etching (e.g., ion
                          beam, etc.)
   216/52
                 (0 OR, 2 XR)
         Class
                 216 : ETCHING A SUBSTRATE:
                                              PROCESSES
         216/52
                       MECHANICALLY SHAPING, DEFORMING, OR ABRADING O
F
                          SUBSTRATE
   225/2
                 (0 OR, 2 XR)
         Class 225: SEVERING BY TEARING OR BREAKING
         225/1
                       METHODS
         225/2
                       .With preliminary weakening
   244/130
                 (0 OR, 2 XR)
         Class 244: AERONAUTICS
         244/117R
                      AIRCRAFT STRUCTURE
         244/129.1
                      .Details
                       .. Aerodynamic resistance reducing
         244/130
   244/204
                 (2 OR, 0 XR)
         Class 244: AERONAUTICS
         244/34R
                       AIRCRAFT SUSTENTATION
         244/35R
                      .Sustaining airfoils
         244/198
                       ..With lift modification
         244/201
                       ...Variable
         244/204
                       .... By controlling boundary layer
   250/492.21
                 (0 OR, 2 XR)
         Class
                 250 : RADIANT ENERGY
         250/492.1
                       IRRADIATION OF OBJECTS OR MATERIAL
                     .Irradiation of semiconductor devices .. Ion bombardment
         250/492.2
         250/492.21
   257/418
                 (0 OR, 2 XR)
                 257 : ACTIVE SOLID-STATE DEVICES
         Class
         257/414
                       RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G.,
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09681304 CLSTITLES CHEMICAL, STRESS, LIGHT, OR MAGNETIC FIE LD SENSORS) 257/415 .Physical deformation 257/417 ..Strain sensors 257/418 ...With means to concentrate stress 2 257/419 (1 OR, 1 XR)257 : ACTIVE SOLID-STATE DEVICES Class 257/414 RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G., CHEMICAL, STRESS, LIGHT, OR MAGNETIC FI ELD SENSORS) 257/415 .Physical deformation 257/417 ..Strain sensors 257/418 ...With means to concentrate stress 257/419With thinned central active portion of semiconductor surrounded by thick insensiti ve portion (e.g., diaphragm type strain gauge) 257/420 (0 OR, 2 XR)257 : ACTIVE SOLID-STATE DEVICES Class 257/414 RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G., CHEMICAL, STRESS, LIGHT, OR MAGNETIC FIEL D SENSORS) .Physical deformation 257/415 257/420 .. Means to reduce sensitivity to physical deformation 2 257/659 (0 OR, 2 XR)Class 257 : ACTIVE SOLID-STATE DEVICES 257/659 WITH SHIELDING (E.G., ELECTRICAL OR MAGNETIC SHIELDING, OR FROM ELECTROMAGNETIC RADIATIO N OR CHARGE PARTICLES) 257/737 (0 OR, 2 XR)Class 257: ACTIVE SOLID-STATE DEVICES COMBINED WITH ELECTRICAL CONTACT OR LEAD 257/734 257/737 .Bump leads 310/268 (0 OR, 2 XR)310 : ELECTRICAL GENERATOR OR MOTOR STRUCTURE Class DYNAMOELECTRIC 310/10 310/40R .Rotary ..Rotor structure 310/261 310/264 ...Armatures

....Disc

310/268

2	315/111.41 (0 Class 315	09681304_CLSTITLES OR, 2 XR) : ELECTRIC LAMP AND DISCHARGE DEVICES: SYSTEMS		
	315/111.01	DISCHARGE DEVICE LOAD WITH FLUENT MATERIAL		
	315/111.21 315/111.41	<u> </u>		
2		OR, 2 XR) : ELECTRIC LAMP AND DISCHARGE DEVICES: SYSTEMS		
	315/111.01 -	DISCHARGE DEVICE LOAD WITH FLUENT MATERIAL SUPPLY TO THE DISCHARGE SPACE		
	315/111.21 315/111.41 315/111.71	.Plasma generatingWith magnetic field		
2	359/198 (1 Class 359 359/196	OR, 1 XR) : OPTICS: SYSTEMS DEFLECTION USING A MOVING ELEMENT OR MEDIUM (OFFSETTING OR CHANGING AT LEAST A PORTIO		
N OF	THE BEAM)			
359/197 .Using a periodically moving element (periodic change of optically reflecting, refracting				
OI	diffracting	element)		
	359/198	Particular mount or driver for element		
	359/223 (0 Class 359 359/196			
	359/223 (0 Class 359	OR, 2 XR) : OPTICS: SYSTEMS DEFLECTION USING A MOVING ELEMENT OR MEDIUM		
	359/223 (0 Class 359 359/196 THE BEAM) 359/223	OR, 2 XR) : OPTICS: SYSTEMS DEFLECTION USING A MOVING ELEMENT OR MEDIUM (OFFSETTING OR CHANGING AT LEAST A PORTION .By moving a reflective element		
OF	359/223 (0 Class 359 359/196 THE BEAM) 359/223	OR, 2 XR) : OPTICS: SYSTEMS DEFLECTION USING A MOVING ELEMENT OR MEDIUM (OFFSETTING OR CHANGING AT LEAST A PORTION .By moving a reflective element OR, 1 XR) : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES ELECTRIC CHARGE GENERATING OR CONDUCTING MEANS		
OF	359/223 (0 Class 359 359/196 THE BEAM) 359/223 361/233 (1 Class 361	OR, 2 XR) : OPTICS: SYSTEMS DEFLECTION USING A MOVING ELEMENT OR MEDIUM (OFFSETTING OR CHANGING AT LEAST A PORTION .By moving a reflective element OR, 1 XR) : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES		
OF	359/223 (0 Class 359 359/196 THE BEAM) 359/223 361/233 (1 Class 361 361/230 361/233 427/523 (0 Class 427	OR, 2 XR) : OPTICS: SYSTEMS DEFLECTION USING A MOVING ELEMENT OR MEDIUM (OFFSETTING OR CHANGING AT LEAST A PORTION .By moving a reflective element OR, 1 XR) : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES ELECTRIC CHARGE GENERATING OR CONDUCTING MEANS (E.G., CHARGING OF GASES) .Use of forces of electric charge or field		

09681304	CLSTITLES
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2 427/524 Class 427/457 427/523 427/524	427	: COATING PROCESSES	
2 427/527 Class 427/457 427/523 427/527	427	: COATING PROCESSES	
2 430/319 Class 430/269	430	: RADIATION IMAGERY CHEMISTRY: PROCESS, COMPOSITION, OR PRODUCT THEREOF IMAGING AFFECTING PHYSICAL PROPERTY OF	
RADIATION SENSITIVE MATERIAL, OR PRODUC G NONPLANAR OR			
OR PRODUCT		PRINTING SURFACE - PROCESS, COMPOSITION,	
430/311 430/319		.Making electrical device Named electrical device	
2 430/5 Class		OR, 1 XR) : RADIATION IMAGERY CHEMISTRY: PROCESS, COMPOSITION, OR PRODUCT THEREOF	
430/4		RADIATION MODIFYING PRODUCT OR PROCESS OF	
430/5		MAKING .Radiation mask	
2 438/107 Class		OR, 1 XR) : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS	
438/106		PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCT	
OR 438/107		.Assembly of plural semiconductive substrates each possessing electrical device	
		OR, 0 XR) : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS	
438/106		PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCT	

OR		09681304_CLSTITLES
OIC	438/120	.With vibration step
2	438/127 Class	R, 2 XR) SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
OR	438/106	PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCT
OK	438/127	.Encapsulating
2	438/26 Class	R, 2 XR) SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
	438/22	MAKING DEVICE OR CIRCUIT EMISSIVE OF
	438/26	NONELECTRICAL SIGNAL .Packaging (e.g., with mounting, encapsulating
,		etc.) or treatment of packaged semiconducto
r		
2	438/28 Class	R, 0 XR) SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
	438/22	MAKING DEVICE OR CIRCUIT EMISSIVE OF NONELECTRICAL SIGNAL
	438/26	.Packaging (e.g., with mounting, encapsulating
,		etc.) or treatment of packaged semiconduct
or	438/28	Plural emissive devices
2	438/34 Class	R, 2 XR) SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
	438/22	MAKING DEVICE OR CIRCUIT EMISSIVE OF
	438/34	NONELECTRICAL SIGNAL .Making emissive array
2	438/406 Class	R, 1 XR) SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/400

438/404

438/406

FORMATION OF ELECTRICALLY ISOLATED LATERAL

..Bonding of plural semiconductive substrates

SEMICONDUCTIVE STRUCTURE

.Total dielectric isolation

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09681304 CLSTITLES
  2 438/456
                   (0 OR, 2 XR)
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          Class
          438/455
                        BONDING OF PLURAL SEMICONDUCTOR SUBSTRATES
          438/456
                        .Having enclosed cavity
  2 438/457
                  (0 \text{ OR}, 2 \text{ XR})
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          Class
          438/455
                        BONDING OF PLURAL SEMICONDUCTOR SUBSTRATES
          438/457
                        .Warping of semiconductor substrate
  2 438/464
                   (0 OR, 2 XR)
          Class
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          438/460
                        SEMICONDUCTOR SUBSTRATE DICING
          438/464
                        .With attachment to temporary support or
                           carrier
  2 438/51
                   (0 OR, 2 XR)
          Class
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          438/48
                        MAKING DEVICE OR CIRCUIT RESPONSIVE TO
                             NONELECTRICAL SIGNAL
          438/50
                        .Physical stress responsive
          438/51
                        .. Packaging (e.g., with mounting,
                           encapsulating, etc.) or treatment of packa
ged
                           semiconductor
   438/692
                  (0 OR, 2 XR)
          Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
          438/689
                        CHEMICAL ETCHING
          438/690
                        .Combined with the removal of material by
                             nonchemical means (e.g., ablating, abradi
ng, etc.)
          438/691
                        .. Combined mechanical and chemical material
                            removal
          438/692
                        ... Simultaneous (e.g., chemical-mechanical
                           polishing, etc.)
  2 438/745
                   (1 OR, 1 XR)
                  438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
         Class
          438/689
                        CHEMICAL ETCHING
          438/745
                        .Liquid phase etching
```

2 438/753 (0 OR, 2 XR)

Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/689 CHEMICAL ETCHING

438/745 .Liquid phase etching

438/753 ..Silicon

2 438/800 (0 OR, 2 XR)

Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/800 MISCELLANEOUS

2 438/933 (0 OR, 2 XR)

Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/933 GERMANIUM OR SILICON OR GE-SI ON III-V

2 445/50 (0 OR, 2 XR)

Class 445: ELECTRIC LAMP OR SPACE DISCHARGE COMPONENT OR

DEVICE MANUFACTURING

445/1 PROCESS

445/46 .Electrode making ..Electrode shaping

445/50 ...Emissive type

2 451/388 (1 OR, 1 XR)

Class 451: ABRADING

451/364 WORK HOLDER

451/388 .Vacuum

09681304 CLS

Most Frequently Occurring Classifications of Patents Returned From A Search of 09681304 on March 13, 2002

```
10
    310/307
  4
   216/2
  4 438/50
  3 148/33.2
  3 257/415
  3 310/40MM
  3 438/460
  3 438/515
  3 438/52
 2
    73/514.16
  2
    73/514.21
  2 118/723E
  2 118/723IR
  2 156/241
 2 156/345
  2
   200/181
 2 204/192.37
  2 244/204
 2 257/417
  2 271/194
 2 310/309
 2 359/291
  2 430/22
  2 438/120
  2 438/28
  2 438/458
Cross-Reference Classifications
  9 438/52
  7 257/417
  6 438/50
  5
    216/2
  5 438/455
  4
    73/514.36
  4 118/728
  4 310/40MM
  3 118/723I
  3 118/723MP
  3 118/733
  3 156/247
 3
    156/267
  3 156/345
    216/67
```

Original Classifications

09681304 CLS

- 3 257/254 3 257/415 3 271/195 310/306 3 310/DIG 6 3 359/230 3 359/290 3 438/459 3 438/48 3 438/526 3 438/53 3 438/706 3 438/712 3 438/739 2 29/596 2 73/514.32 2 73/654 2 118/723IR 2 156/230 2 156/233 2 156/250 2 156/256 2 204/192.32 2 204/298.15 2 204/298.32 2 204/298.36
- 2 216/52
- 2 225/2
- 2 244/130
- 2 250/492.21
- 2 257/418
- 2 257/420
- 2 257/659
- 2 257/737
- 2 310/268
- 2 315/111.41
- 2 315/111.71
- 2 359/223
- 2 359/224
- 2 427/523
- 2 427/524
- 2 427/527
- 2 430/319
- 2 438/127
- 2 438/26
- 2 438/34
- 2 438/456
- 438/457

- 2 438/464
- 2 438/51
- 2 438/692
- 2 438/753
- 2 438/800
- 2 438/933
- 2 445/24
- 2 445/50

Combined Classifications

- 12 438/52
- 11 310/307
- 10 438/50
 - 9 216/2
 - 9 257/417
 - 7 310/40MM
 - 6 257/415
 - 6 438/455
 - 5 156/345
 - 4 73/514.36
 - 4 118/723IR
 - 4 118/728
 - 4 257/254
 - 4 310/306
 - 4 438/460
 - 4 438/526
 - 4 438/53
 - 3 73/514.21
 - 3 118/723E
 - 3 118/723I
 - 3 118/723MP
 - 3 118/733
 - 3 148/33.2
 - 3 156/247
 - 3 156/267
 - 3 200/181
 - 3 204/298.15
 - 3 216/67
 - 3 271/194
 - 3 271/195
 - 3 310/309
 - 3 310/DIG 6
 - 3 359/224
 - 3 359/230
 - 3 359/290
 - 3 359/291
 - 3 430/22
 - 3 438/458

09681304 CLS

- 3 438/459 3 438/48 3 438/515 438/706 3 438/712 3 438/739 3 445/24 2 29/596 2 29/598 2 73/514.16 2 73/514.32 2 73/654 2 156/230 2 156/233 2 156/241 2 156/250 2 156/256 2 156/344 2 204/192.32 2 204/192.37 2 204/298.32 2 204/298.36 2 216/52 2 225/2 2 244/130 2 244/204 2 250/492.21 2 257/418 2 257/419 2 257/420 2 257/659 2
- 2 359/223

2

2

2

2

257/737

310/268

359/198

315/111.41

315/111.71

- 2 361/233
- 2 427/523
- 2 427/524
- 2 427/527
- 2 430/319
- 2 430/5
- 2 438/107
- 2 438/120
- 2 438/127
- 2 438/26
- 438/28

09681304_CLS

- 2 438/34 2 438/406 2 438/456 2 438/457 2 438/51 2 438/51 2 438/692 2 438/745 2 438/753 2 438/800 2 438/933 2 445/50 2 451/388

09681304 QUAL

09681304_QUAL

09681304_QUAL

6033974	65
6039316	65
6040935	65
6048411	65
6051073	65
6058778	65
6058778	65
6065864	65
6113735	65
6114188	65
6119052	65
6119052 6116863 6120660	65 65
6120660	65
6123985	65
6134042	65
6137206	65
6136243	65
6143583	65 65
6143997 6146979	65
6146227	65 65 65
6149190	65
6153524	65 65
6155490	65
6155909	65 65
6156652	65
6156652 6159824 6159825	65 65
6159825	65
6162705	65
6166478	65 65
6169321	65
6170332	65
6171879 6171965	65 65
6171965	65
6184111	65
6186091	65
6187110	65
6193501	65
6199575	65
6199874	65
6204151	65 65
6207005	65 65
6210514	65 65
6213050 6217724	65
6217724	65
6218209	65
6218762	65
0210702	55

.09681304_QUAL

6220096	65
6210514	65
6213050	65
6217724	65
6218205	65
6218209	65